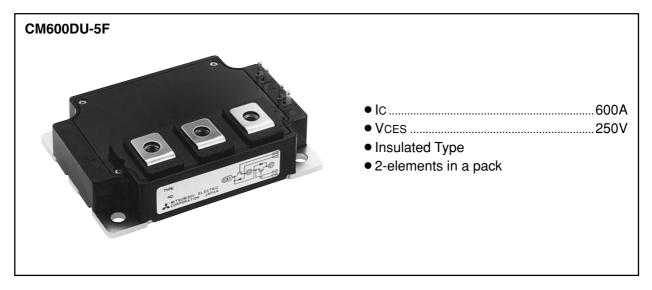
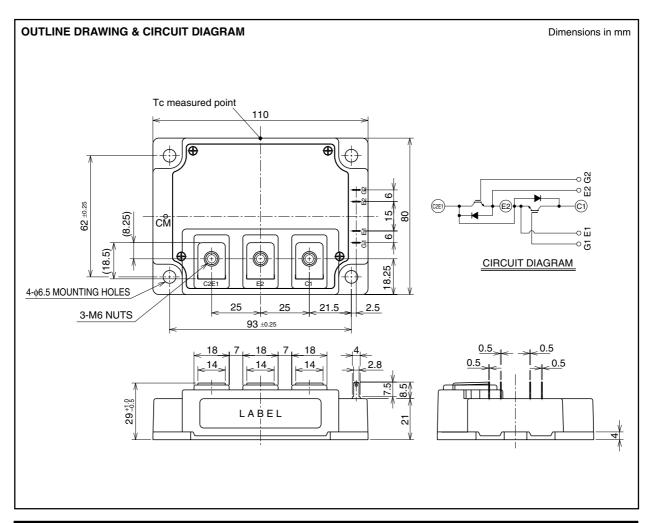
HIGH POWER SWITCHING USE



APPLICATION

AC moter controll of forklift (battery power source)





HIGH POWER SWITCHING USE

MAXIMUM RATINGS (Tj = 25°C, unless otherwise specified)

Symbol	Parameter	Conditions		Ratings	Unit
VCES	Collector-emitter voltage	G-E Short		250	V
VGES	Gate-emitter voltage	C-E Short		±20	V
Ic	Collector current	Tc = 25°C		600	Α
IC(rms)				350	A(rms)
Ісм		Pulse (N	Note 2)	1200	Α
IE (Note 1)	Emitter current	Tc = 25°C		600	Α
IE(rms) (Note 1)				350	A(rms)
IEM (Note 1)		Pulse (N	Note 2)	1200	Α
PC (Note 3)	Maximum collector dissipation	Tc = 25°C		1100	W
Tj	Junction temperature			− 40 ~ +150	°C
Tstg	Storage temperature			− 40 ~ +125	°C
Viso	Isolation voltage	Terminals to base plate, f = 60Hz, AC 1 minute		2500	Vrms
_	Torque strength	Main terminals M6 screw		3.5 ~ 4.5	N•m
		Mounting M6 screw		3.5 ~ 4.5	N•m
_	Weight	Typical value		580	g

ELECTRICAL CHARACTERISTICS (Tj = 25°C, unless otherwise specified)

Cumbal	Darameter	Test conditions		Limits			1.1
Symbol	Parameter			Min.	Тур.	Max.	Unit
ICES	Collector cutoff current	VCE = VCES, VGE = 0V		_	1	1	mA
VGE(th)	Gate-emitter threshold voltage	IC = 60mA, VCE = 10V		3.0	4.0	5.0	٧
IGES	Gate leakage current	±VGE = VGES, VCE = 0V		_	_	0.5	μΑ
VCE(sat)	Collector-emitter saturation voltage	IC = 600A VGE = 10V □	Γj = 25°C	_	1.2	1.7	V
			∫j = 125°C	_	1.1	_	
Cies	Input capacitance	Vo= 40V		_	_	170	nF
Coes	Output capacitance	VCE = 10V	_	_	11		
Cres	Reverse transfer capacitance	VGE = 0V		_	1	5.7	
QG	Total gate charge	VCC = 100V, IC = 600A, VGE = 10V		_	2200	_	nC
td(on)	Turn-on delay time	Vcc = 100V, lc = 600A $VGE = \pm 10V$ $RG = 4.2\Omega, Inductive load IE = 600A$		_	-	850	ns
tr	Turn-on rise time			_	_	600	
td(off)	Turn-off delay time			_	_	1100	
tf	Turn-off fall time			_		500	
trr (Note 1)	Reverse recovery time			_	_	300	ns
Qrr (Note 1)	Reverse recovery charge			_	20.0	_	μC
VEC(Note 1)	Emitter-collector voltage	IE = 600A, VGE = 0V		_	-	2	V
Rth(j-c)Q	*1	IGBT part (1/2 module)		_	_	0.11	K/W
Rth(j-c)R	Thermal resistance*1	FWDi part (1/2 module)		_	-	0.20	
Rth(c-f)	Contact thermal resistance	Case to heat sink, Thermal compound applied*2 (1/2 module)		_	0.02	_	
Rth(j-c')Q	Thermal resistance*3	Case temperature measured point is just under the chips			1	0.05	

Note 1. IE, VEC, trr, Qrr & die/dt represent characteristics of the anti-parallel, emitter-collector free-wheel diode (FWDi).



Feb. 2009

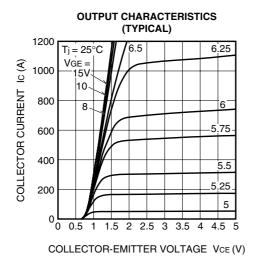
^{2.} Pulse width and repetition rate should be such that the device junction temperature (Tj) does not exceed Tjmax rating.

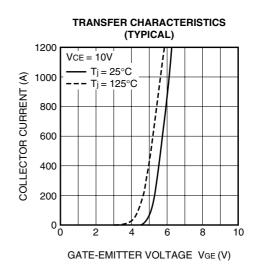
^{3.} Junction temperature (Tj) should not increase beyond 150°C.

^{4.} Pulse width and repetition rate should be such as to cause negligible temperature rise.
*1 : Case temperature (Tc) measured point is indicated in OUTLINE DRAWING.
*2 : Typical value is measured by using thermally conductive grease of λ = 0.9[W/(m • K)].
*3 : If you use this value, Rth(f-a) should be measured just under the chips.

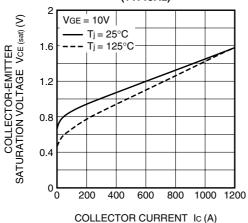
HIGH POWER SWITCHING USE

PERFORMANCE CURVES

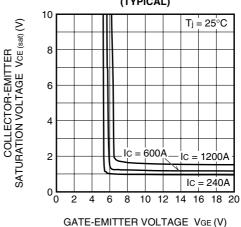


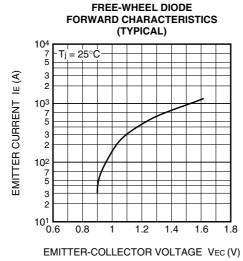


COLLECTOR-EMITTER SATURATION VOLTAGE CHARACTERISTICS (TYPICAL)

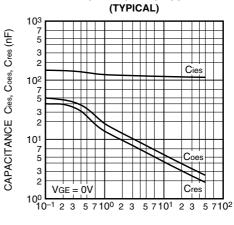


COLLECTOR-EMITTER SATURATION
VOLTAGE CHARACTERISTICS
(TYPICAL)





CAPACITANCE-VCE CHARACTERISTICS

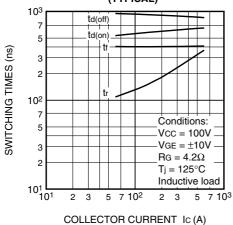


COLLECTOR-EMITTER VOLTAGE VCE (V)

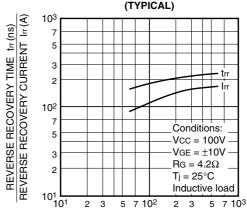


HIGH POWER SWITCHING USE

HALF-BRIDGE SWITCHING CHARACTERISTICS (TYPICAL)

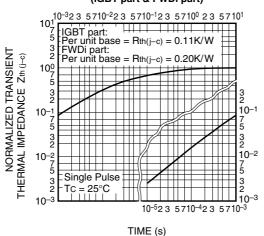


REVERSE RECOVERY CHARACTERISTICS OF FREE-WHEEL DIODE (TYPICAL)

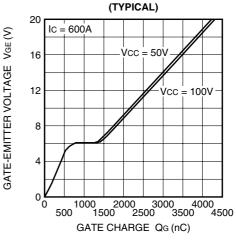


EMITTER CURRENT IE (A)

TRANSIENT THERMAL IMPEDANCE CHARACTERISTICS (IGBT part & FWDi part)



GATE CHARGE CHARACTERISTICS





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